

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Akira CHINDA et al.

Title: WIRING BOARD, SEMICONDUCTOR DEVICE, AND
PROCESS FOR PRODUCTION OF WIRING BOARD

Appl. No.: Unassigned

Filing Date: December 19, 2001

Examiner: Unassigned

Art Unit: Unassigned

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PRELIMINARY AMENDMENT

Commissioner for Patents
Washington, D.C. 20231

Sir:

Prior to examination of the present Application, Applicants respectfully request that the above-identified application be amended as follows:

IN THE CLAIMS:

In accordance with 37 CFR § 1.121, please substitute for original claim 2, the following rewritten version of the same claim, as amended, and please renumber claims 40 - 43 (1st Claim 43) as claims 39-42 as shown below. The changes are shown explicitly in the attached "Versions With Markings to Show Changes Made."

91 2. (Amended) A wiring board as claimed in claim 1, wherein:
a thickness of said conductive member is $\frac{1}{2}$ or more of that of said insulating substrate.

39. (Amended) A process for the production of a wiring board as claimed in claim 37, wherein:
02 a step for forming said conductive member is effected by forming a copper (Cu) plating or a nickel (Ni) plating in accordance with electroplating method.

40. (Amended) A process for the production of a wiring board as claimed in claim 38, wherein:
a step for forming said conductive member is effected by forming a copper (Cu) plating or a nickel (Ni) plating in accordance with electroplating method.